



Interconnects for Electronics Packaging

Guest Editors:

Dr. Ali Roshanghias

Heterogeneous Integration
Technologies, Silicon Austria
Labs (SAL) GmbH, 9524 Villach,
Austria

Prof. Dr. Ha Duong Ngo

Hochschule für Technik und
Wirtschaft Berlin, University of
Applied Sciences, Treskowallee 8,
10318 Berlin, Germany

Deadline for manuscript
submissions:

closed (31 January 2023)

Message from the Guest Editors

Advanced heterogeneous integration as the key enabler of the “more than Moore” era demands disruptive interconnects technologies. These interconnects enable 3D integration, chip embedding, and enhanced thermal and electrical performances, which lead to device shrinkage, an increase in computing efficiency, superior switching speed, and power. The continued scaling of interconnects has faced cost, integration, thermal, and reliability challenges, which require innovations in terms of both technologies and materials. This Special Issue will cover the most advanced and emerging interconnects. A reliability analysis and failure analysis of the emerging interconnects will also be addressed here. We encourage original research works describing novel interconnecting technologies, materials and processes that can potentially lead to significant advances in the field of microelectronics packaging.

The deadline to submit papers to this special issue is 31 January 2023. However, papers submitted in advance will be peer-reviewed and may be published well before this deadline. For more details, please click [here](#).





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Editor-in-Chief

Prof. Dr. Flavio Canavero

Department of Electronics and
Telecommunications,
Politecnico di Torino, 10129
Torino, Italy

Message from the Editor-in-Chief

Electronics is a multidisciplinary journal designed to appeal to a diverse audience of research scientists, practitioners, and developers in academia and industry. The journal is devoted to fast publication of latest technological breakthroughs, cutting-edge developments, and timely reviews of current and emerging technologies related to the broad field of electronics. Experimental and theoretical results are published as regular peer-reviewed articles or as articles within Special Issues guest-edited by leading experts in selected topics of interest.

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Electronics Editorial Office
MDPI, St. Alban-Anlage 66
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